

Supplementary material

Direct Laser Writing of Copper Micropatterns from Deep Eutectic Solvents Using Pulsed near-IR Radiation

Ekaterina A. Avilova ¹, Evgeniia M. Khairullina ^{2,3}, Andrey Yu. Shishov ², Elizaveta A. Eltysheva ¹, Vladimir Mikhailovskii ², Dmitry A. Sinev ¹ and Ilya I. Tumkin ^{2,*}

¹ School of Physics and Technology, ITMO University, 197101 St. Petersburg, Russia; eaavilova@itmo.ru (E.A.A.); e.a.eltyseva@itmo.ru (E.A.E.); sinev@itmo.ru (D.A.S.)

² Institute of Chemistry, Saint Petersburg State University, 199034 St. Petersburg, Russia; e.khayrullina@spbu.ru (E.M.K.); andrey.shishov.rus@gmail.com (A.Y.S.); v.mikhailovskii@gmail.com (V.M.)

³ SCAMT Laboratory, ITMO University, 197101 St Petersburg, Russia

* Correspondence: i.i.tumkin@spbu.ru

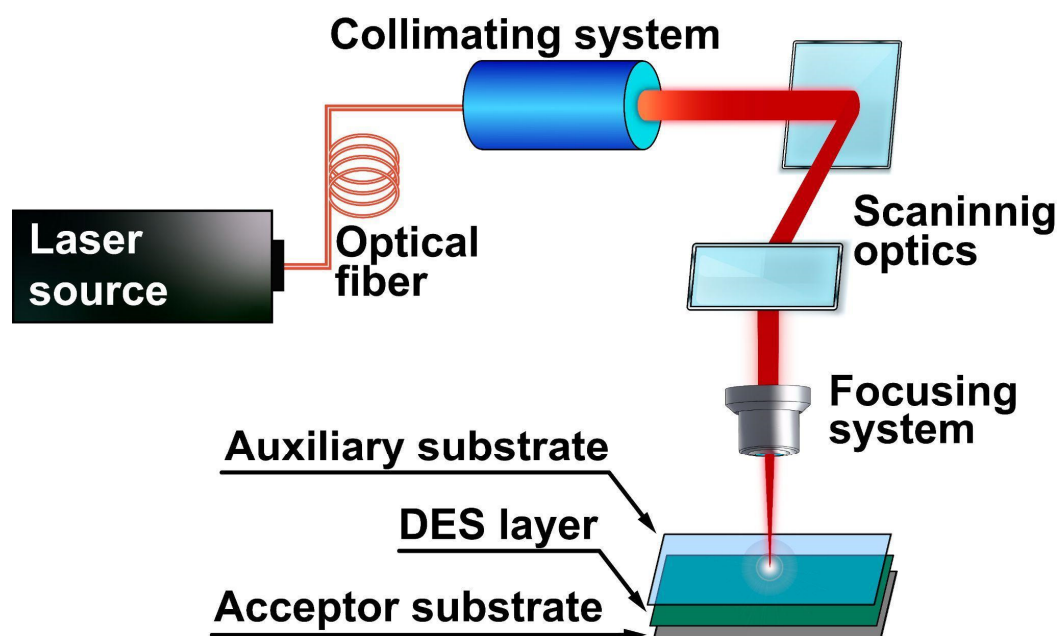


Figure S1. Scheme of a laser setup for laser-induced copper deposition from eutectic solvents.

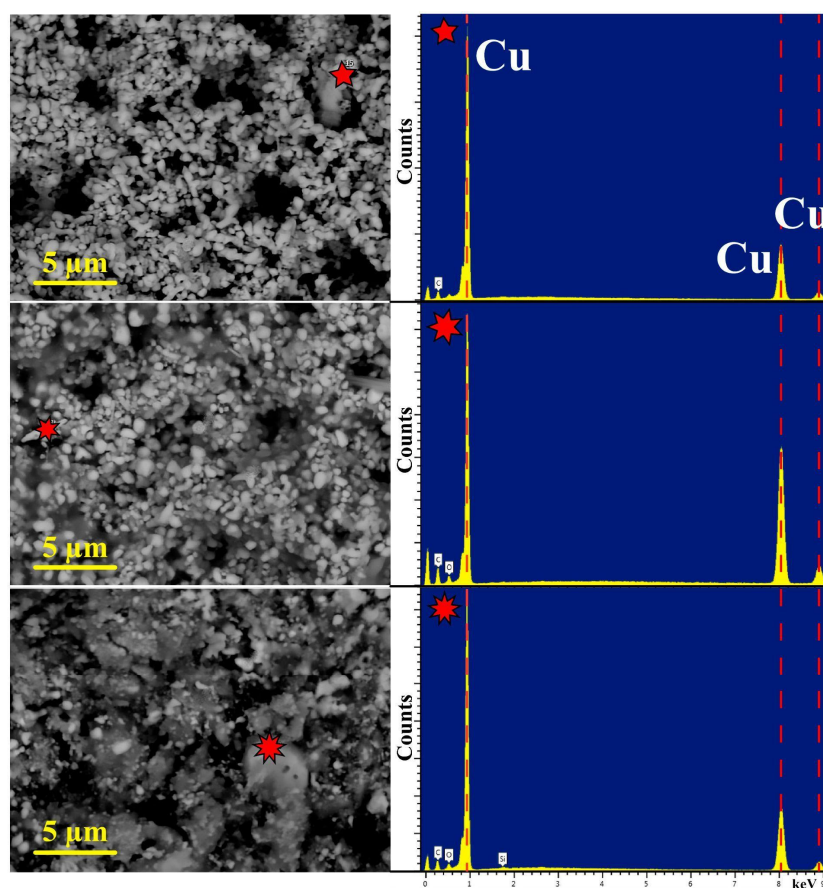


Figure S2. EDX spectra of copper track on laser-treated and non-cleaned substrate in three different random spot.

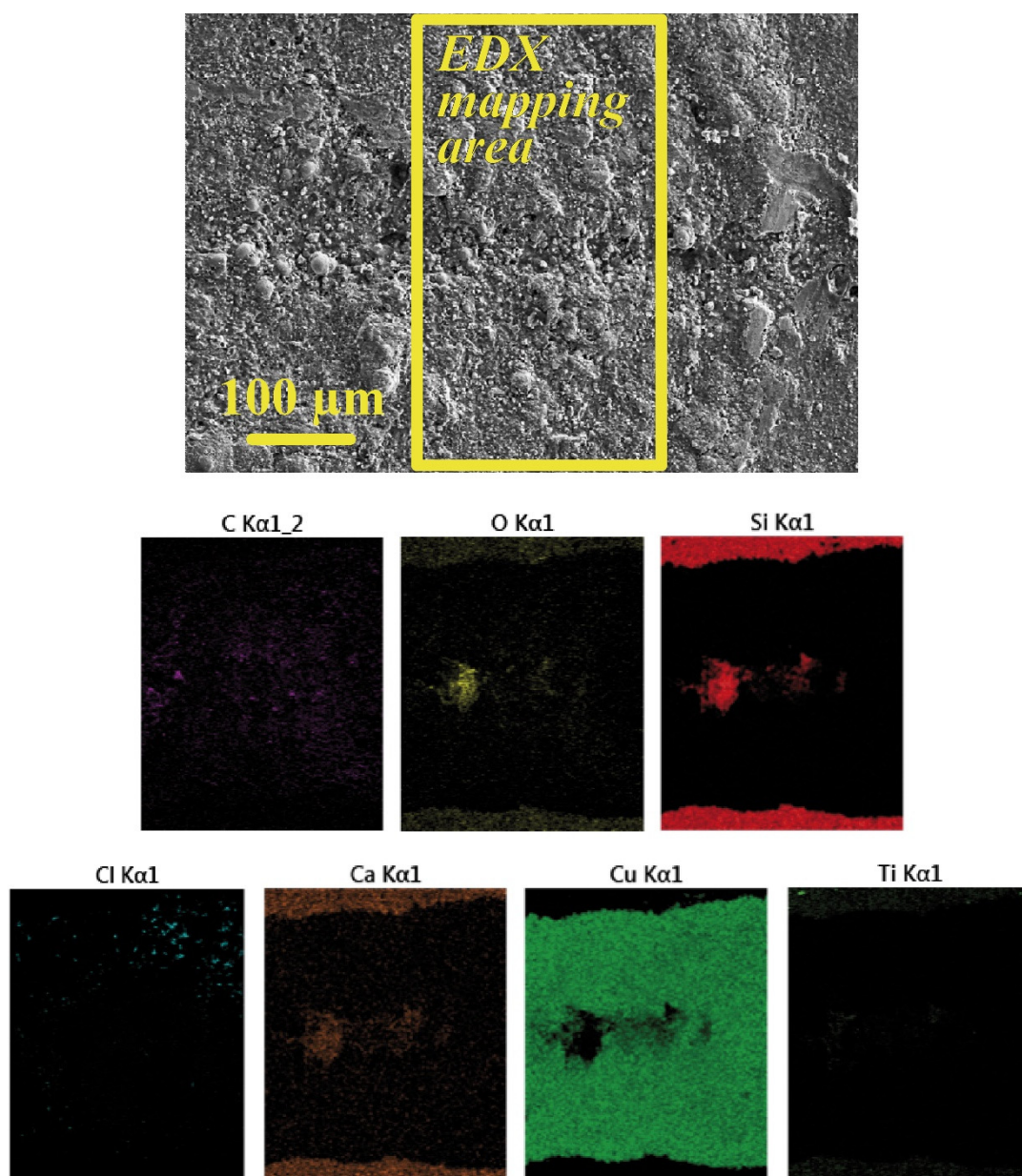


Figure S3. EDX mapping of the manufactured pattern.